

# Data and Facts

## 2010

### SMT Assembly

Maximum output:	1500 million assemblies p. a.
Minimum assembly dimensions:	Type 0201
Maximum assembly dimensions:	70 mm x 30 mm
Fine pitch placement:	To 0.3 mm
Circuit board dimensions:	Max. 368 mm x 500 mm

#### Reflow:

- Vapour phase reflow
- Convection reflow

All fully automated reflow processes performed in a controlled nitrogen atmosphere (protective gas) and are available as leaded and unleaded processes.

### THT Assembly

Maximum assembly output:	80 million assemblies p. a.
Automated assembly preparation	
Semi-automatic assembly with laser assembly benches	
Double wave soldering	
Selective soldering	
Board dimensions:	Max. 350 mm x 500 mm

All fully automated soldering processes performed in a controlled nitrogen atmosphere (protective gas) and are available as leaded and unleaded processes.

### PCB Protection

Selective coating systems with conveyor oven	400 mm x 400 mm
Fully automated PCB encapsulation ("Macromelt") using hot melt moulding technology	

### Cable Assembly

Fully automated single strand production	
Semi-automatic cable production	
IDC technology	
Crimping technology	
Soldering technology	
Semi and fully automated adhesive and encapsulation technology	

### Testing

■ In-circuit-testing	■ Fully automated X-ray testing
■ Functional testing	■ Automatic visual inspection
■ Climatic testing	■ Combined testing
■ Burn-In testing	■ Safety category testing
■ Run-In testing	■ Custom testing
■ High voltage testing	■ Polished section analysis for soldered and crimp connections
■ Cable testers	
■ Sequential manufacturing testing system	

### Certification

■ DIN EN ISO 9001	■ DIN EN 13485
■ DIN EN 14001	■ TS 16949

### Good partnership counts

Good, reliable partners and suppliers are key factors that help us to maintain our competitive edge. Here is a selection of our partners in the field of machinery and equipment:

